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Invensas Licenses BVA® Vertical Interconnect Technology to Tong Hsing for MEMS Applications

SAN JOSE, Calif.--(BUSINESS WIRE)-- Invensas Corporation, a wholly owned subsidiary of Tessera Technologies, Inc. (Nasdaq:TSRA), today announced that Tong Hsing Electronic Industries Ltd., a leading Taiwanese provider of microelectronic packaging and substrate manufacturing services, has entered into a license agreement for Invensas' Bond Via Array™ (BVA®) vertical interconnect technology. In addition, the companies have completed technology transfer and qualification of the BVA platform.

The increasing functionality of smartphones, wearables and Internet of Things (IoT) devices is driving a requirement for low cost, small form-factor micro-electromechanical systems (MEMS) devices and system-in-package (SiP) solutions. BVA readily addresses this market requirement by leveraging existing manufacturing infrastructure and eliminating the need for expensive interconnect processes such as laser drilling, copper plating or through-silicon-vias.

"Cost effective and robust vertical interconnect technology is critically important for the miniaturization of next generation electronics," said Craig Mitchell, President of Invensas. "We are pleased with our collaboration with Tong Hsing to commercialize BVA technology to meet this market need and look forward to continuing our partnership."

"It has been a great pleasure to work with Invensas team to evaluate and qualify the BVA technology platform," said Heinz Ru, President of Tong Hsing. "We look forward to providing BVA packaging services to the MEMS industry."

About Tessera Technologies, Inc.

Tessera Technologies, Inc., including its Invensas, FotoNation and Ziptronix subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D-IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and products and solutions for mobile and computational imaging, including our LifeFocus™, FaceTools™, FacePower™, FotoSavvy™, DigitalAperture™, face beautification, red-eye removal, High Dynamic Range, autofocus, panorama, and image stabilization intellectual property. For more information call +1.408.321.6000 or visit www.tessera.com or www.invensas.com.

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Safe Harbor Statement

This document contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the characteristics, benefits, and features of BVA technology and the use of BVA by Tong Hsing. Material factors that may cause results to differ from the statements made include the plans or operations relating to the businesses of Tessera Technologies, Inc. (the "Company"); market or industry conditions; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; initiation, delays, setbacks or losses relating to the Company's intellectual property or intellectual property litigations, or invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; the risk of a decline in demand for semiconductors and products utilizing FotoNation technologies; failure by the industry to use technologies covered by the Company's patents; the expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies due to high concentration in the markets for semiconductors and related products and smartphone imaging; and the impact of competing technologies on the demand for the Company's technologies. You are

cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release. The Company's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended Dec. 31, 2014 and its Quarterly Report on Form 10-Q for the quarter ended Sept. 30, 2015, include more information about factors that could affect the Company's financial results. The Company assumes no obligation to update information contained in this press release. Although this release may remain available on the Company's website or elsewhere, its continued availability does not indicate that the Company is reaffirming or confirming any of the information contained herein.

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